12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20140701000
Qualification of CK5000A Mold Compound in AP1 for PDIP packages
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

PCN# 20140701000
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20140701000	**PCN Date:**	07/10/2014
Title:	Qualification of CK5000A Mold Compound in AP1 for PDIP packages		
Customer Contact:	PCN Manager	**Phone:** +1(214)480-6037	**Dept:** Quality Services
Proposed 1st Ship Date:	10/10/2014	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the Qualification of CK5000A Mold Compound in Amkor Philippines (AP1) for PDIP packages.

	Change From:	***Change To:***
Mold Compound	DMC2000HG, DMC200NF	CK5000A

Reason for Change:

Discontinuation of DMC2000HG & DMC200NF mold compound by Amkor Philippines (AP1).

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None

Product Affected:

ADC0831CCN/NOPB	DS75176BN/NOPB	LM2574HVN-ADJ/NOPB	LM6144BIN/NOPB
ADC0832CCN/NOPB	DS75176BTN/NOPB	LM2574N-12/NOPB	LM78S40N/NOPB
ADC0834CCN/NOPB	DS96174CN	LM2574N-3.3/NOPB	LMC6041IN/NOPB
AM26LS31PC	DS96174CN/NOPB	LM2574N-5.0	LMC6042AIN/NOPB
DS14C88N	DS96175CN/NOPB	LM2574N-5.0/NOPB	LMC6064IN/NOPB
DS14C89AN	DS96176CN/NOPB	LM2574N-ADJ/NOPB	LMC6462BIN/NOPB
DS14C89AN/NOPB	LF353N/NOPB	LM2578AN/NOPB	LMC6464BIN/NOPB
DS26C31TN	LF398AN/NOPB	LM2671N-5.0/NOPB	LMC6484AIN
DS26C31TN/NOPB	LF412ACN/NOPB	LM2672N-5.0/NOPB	LMC6484IN
DS26LS31CN	LF412CN/NOPB	LM2674N-ADJ/NOPB	LMC6484IN/NOPB
DS26LS31CN/NOPB	LHV720NA/NOPB	LM2675N-ADJ/NOPB	LMC660AIN/NOPB
DS26LS31N	LM13700N/NOPB	LM2902N/NOPB	LMC660CN/NOPB
DS3658N	LM2524DN	LM318N	LME49740NA/NOPB
DS3658N/NOPB	LM2524DN/NOPB	LM318N/NOPB	TP3054N/NOPB
DS3668N/NOPB	LM2574HVN-12/NOPB	LM319N/NOPB	TP3057N/NOPB
DS3695N/NOPB	LM2574HVN-15/NOPB	LM331N/NOPB	
DS3695TN/NOPB	LM2574HVN-5.0	LM3578AN/NOPB	
DS485N/NOPB	LM2574HVN-5.0/NOPB	LM386N-1	

Qualification Report

PDIP mold compound DMC2000HG discontinuance in AP1
Approved06/10/2014

Product Attributes

Attributes	Qual Device: LF444CN/NOPB	Qual Device: LM319N
Assembly Site	AP1	AP1
Package Family	PDIP	PDIP
Wafer Fab Supplier	GL	GL
Wafer Fab Process	BPBIFET.13.1	BPSLM.8.1

- QBS: Qual By Similarity

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LF444CN/NOPB	Qual Device: LM319N
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	-	3/231/0
AC	Autoclave 121C	96 Hours	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	3/231/0	-

-- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20130502-84221

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com